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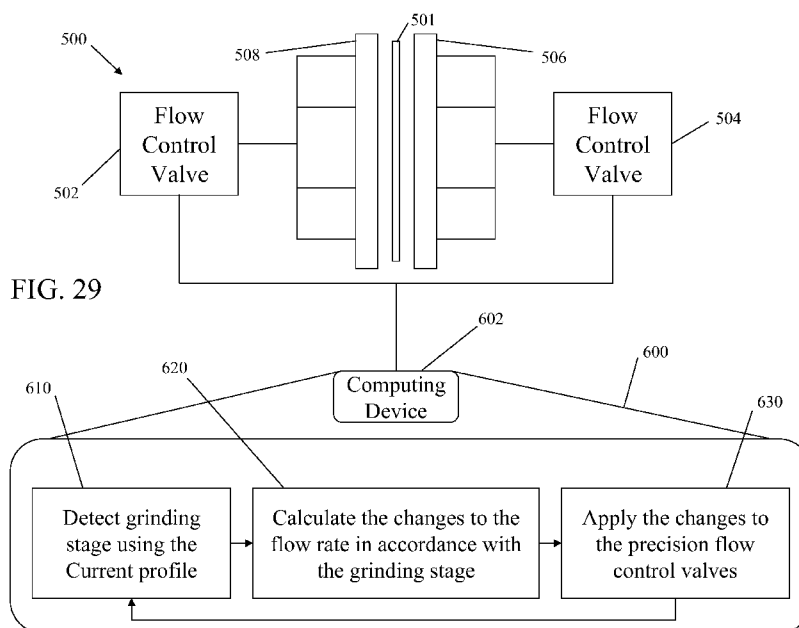
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(54) Title: HYDROSTATIC PAD PRESSURE MODULATION IN A SIMULTANEOUS DOUBLE SIDE WAFER GRINDER



(57) Abstract: Systems and methods are disclosed for modulating the hydrostatic pressure in a double side wafer grinder having a pair of grinding wheels. The systems and methods use a processor to measure the amount of electrical current drawn by the grinding wheels. Pattern detection software is used to predict a grinding stage based on the measured electrical current. The hydrostatic pressure is changed by flow control valves at each stage to change the clamping pressure applied to the wafer and to thereby improve nanotopology in the processed wafer.



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